MOSFET – Power, Single N-Channel 60 V, 6.1 mΩ, 71 A

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFS5C670NLWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant



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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
60 V	6.1 mΩ @ 10 V	71 A
00 V	8.8 mΩ @ 4.5 V	

MAXIMUM RATINGS	(T _J = 25°0	C unless otherw	vise noted)		
Parar	neter		Symbol	Value	Unit
Drain-to-Source Voltag	е		V _{DSS}	60	V
Gate-to-Source Voltage	Э		V _{GS}	±20	V
Continuous Drain		$T_C = 25^{\circ}C$	I _D	71	А
Current R _{θJC} (Notes 1, 3)	Steady	T _C = 100°C		50	
Power Dissipation	State	$T_{C} = 25^{\circ}C$	PD	61	W
$R_{\theta JC}$ (Note 1)		$T_{\rm C} = 100^{\circ}{\rm C}$		31	
Continuous Drain		T _A = 25°C	۱ _D	17	А
Current R _{θJA} (Notes 1, 2, 3)	Steady	$T_A = 100^{\circ}C$		12	
Power Dissipation	State	T _A = 25°C	PD	3.6	W
$R_{\theta JA}$ (Notes 1 & 2)		T _A = 100°C		1.8	
Pulsed Drain Current	T _A = 25	°C, t _p = 10 μs	I _{DM}	440	А
Operating Junction and	Storage T	emperature	T _J , T _{stg}	–55 to + 175	°C
Source Current (Body D)iode)		I _S	68	А
Single Pulse Drain-to-S Energy (I _{L(pk)} = 3.6 A)	Source Av	alanche	E _{AS}	166	mJ
Lead Temperature for S (1/8" from case for 10 s		Purposes	ΤL	260	°C
Stresses exceeding those	listod in t	ho Maximum R	atings table	may dam	ano the

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

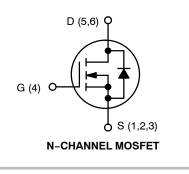
THERMAL RESISTANCE MAXIMUM RATINGS

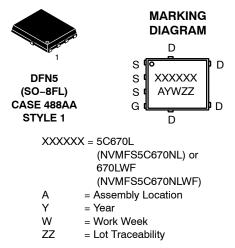
Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	2.4	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	41	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.





ORDERING INFORMATION

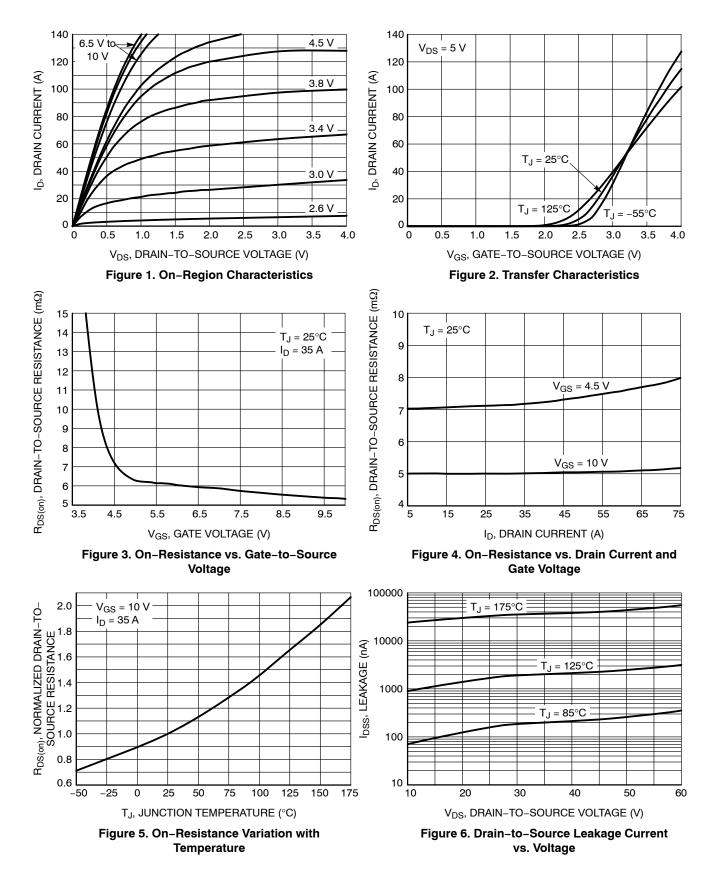
See detailed ordering, marking and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = $25^{\circ}C$ unless otherwise specified)

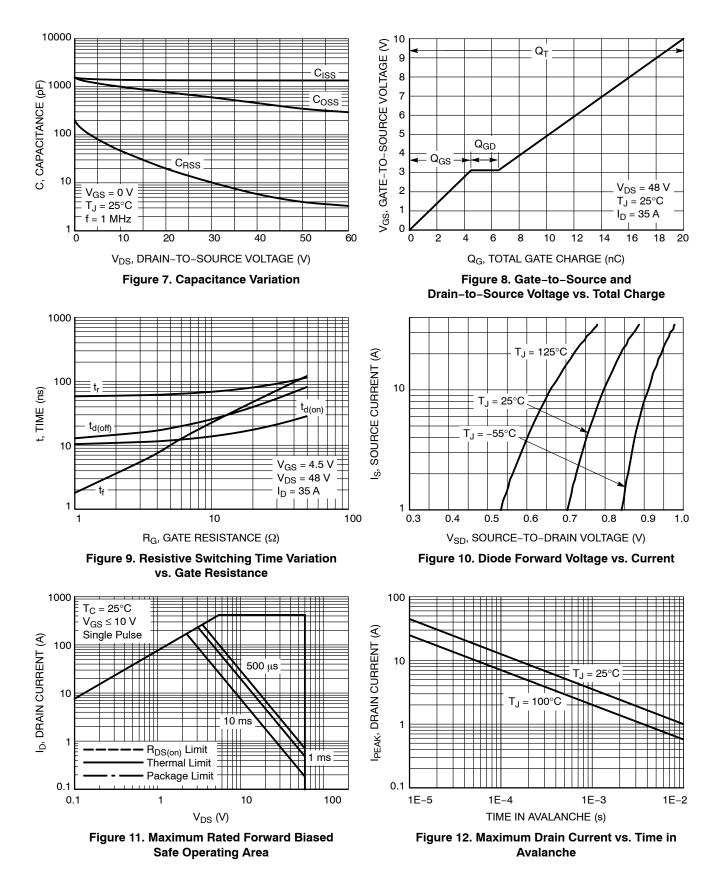
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS	<u>.</u>	-						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D = 250 μ A		60			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				27		mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V,$	T _J = 25 °C			10		
		V _{DS} = 60 V	T _J = 125°C			250	μΑ	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS}$	₆ = 20 V			100	nA	
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= 53 μA	1.2		2.0	V	
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-4.7		mV/°C	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 35 A		5.1	6.1	0	
		V _{GS} = 4.5 V	I _D = 35 A		7.0	8.8	mΩ	
Forward Transconductance	9FS	V _{DS} = 15 V, I _E	₎ = 35 A		82		S	
CHARGES AND CAPACITANCES								
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V			1400		pF	
Output Capacitance	C _{OSS}				690			
Reverse Transfer Capacitance	C _{RSS}				15			
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 4.5 V, V_{DS} = 48 V; I_{D} = 35 A			9.0		nC	
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 48 V; I _D = 35 A			20		nC	
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 10 V, V _{DS} = 48 V; I _D = 35 A			2.5		nC	
Gate-to-Source Charge	Q _{GS}				4.5			
Gate-to-Drain Charge	Q _{GD}				2.0			
Plateau Voltage	V _{GP}				3.1		V	
SWITCHING CHARACTERISTICS (Note 5)							
Turn-On Delay Time	t _{d(ON)}				11			
Rise Time	tr	V_{GS} = 4.5 V, V_{DS} = 48 V, I _D = 35 A, R _G = 2.5 Ω			60		ns	
Turn-Off Delay Time	t _{d(OFF)}				15			
Fall Time	t _f				4			
DRAIN-SOURCE DIODE CHARACTERIS	TICS				•			
Forward Diode Voltage	V _{SD}	$V_{GS} = 0 V$, $T_J = 25^{\circ}C$		0.9	1.2	- v		
		$I_{\rm S} = 35 \rm{A}$ $T_{\rm J} = 125^{\circ}\rm{C}$			0.8			
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dI _S /d _t = 100 A/μs, I _S = 35 A			34			
Charge Time	ta				17		ns	
Discharge Time	t _b				17			
Reverse Recovery Charge	Q _{RR}				19		nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width $\leq 300 \,\mu$ s, duty cycle $\leq 2\%$. 5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

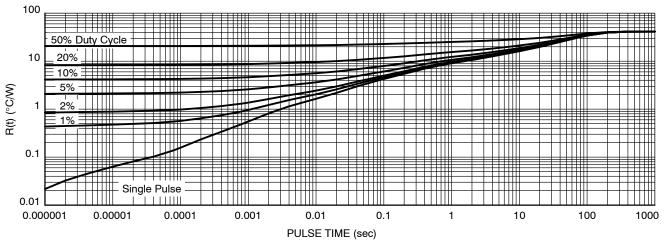


Figure 13. Thermal Characteristics

Device	Device Marking Packag		Shipping [†]	
NVMFS5C670NLT1G	5C670L	DFN5 (Pb-Free)	1500 / Tape & Reel	
NVMFS5C670NLWFT1G	670LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel	
NVMFS5C670NLT3G	5C670L	DFN5 (Pb-Free)	5000 / Tape & Reel	
NVMFS5C670NLWFT3G	670LWF	DFN5 (Pb-Free, Wettable Flanks)	5000 / Tape & Reel	
NVMFS5C670NLAFT1G	5C670L	DFN5 (Pb-Free)	1500 / Tape & Reel	
NVMFS5C670NLWFAFT1G	670LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel	
NVMFS5C670NLWFAFT3G	670LWF	DFN5 (Pb-Free, Wettable Flanks)	5000 / Tape & Reel	

DEVICE ORDERING INFORMATION

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





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